

LAN Modules

Series/Type: **B78477P1***A*14**

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B78477P1007A114		2014-04-25	2014-07-31	2014-10-31
B78477P1006A114		2014-04-25	2014-07-31	2014-10-31
B78477P1005A314		2014-04-25	2014-07-31	2014-10-31

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Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B78477P1004A314		2014-04-25	2014-07-31	2014-10-31
B78477P1003A014		2014-04-25	2014-07-31	2014-10-31
B78477P1002A014		2014-04-25	2014-07-31	2014-10-31
B78477P1001A314		2014-04-25	2014-07-31	2014-10-31

For further information please contact your nearest EPCOS sales office, which will also support you in selecting a suitable substitute. The addresses of our worldwide sales network are presented at www.epcos.com/sales.

Applications

- Local Area Networks using Ethernet protocol
- Hubs, switches, routers
- ADSL modems
- Industrial automation equipment using Ethernet protocol for communication

Features

- Fully compliant with IEEE 802.3, IEEE 802.3af (B78477P1001A314)
- With EMI fingers for shielding
- High electrical performance and EMI suppression
- Optimized for all major transceiver ICs
- Industry standard footprint
- RoHS-compatible

Construction

- Housing: Thermoplastic, UL 94 V-0
- Shield: Ni plated on copper alloy
- Contact: Phosphor bronze, 1.27 μm (50 $\mu\text{''}$) Ni underplating, 0.4 μm (15 $\mu\text{''}$) selective gold plating
- Connector dimensions comply with TIA-968 (FCC 68.5) dimension requirements

Marking

- EPCOS, middle block of ordering code, date code

Delivery mode and packing unit

- Blister trays in carton box
- Packing unit: 512 pcs. per carton box (8 trays), B78477P1001A314: 640 pcs.

Overview and ordering codes

Operating temperature range	LED (left - right)	Ordering code
0 °C ... +70 °C	Green - yellow	B78477P1004A314
	Green - yellow	B78477P1005A314
	Yellow - green	B78477P1006A114
	Yellow - green	B78477P1007A114
	—	B78477P1003A014
–40 °C ... +85 °C	Green - yellow	B78477P1001A314
	—	B78477P1002A014

Mechanical characteristics

Insertion force	20 N max.
Retention force	75 N min.
Durability	750 mating cycles min.

LED specification

LED colour	Wave length	Forward voltage	
		Max.	Typical
Green	565 nm	2.6 V	2.2 V
Yellow	585 nm	2.6 V	2.1 V

Characteristics

B78477P1001A314

(electrical specifications at +25 °C)

Turns ratio (primary : secondary)	1.414 : 1 $\pm$ 3%	
Inductance L	350 μ H min.	100 kHz, 100 mV, 8 mA DC bias
Voltage test V_{test} (primary : secondary) (primary : shield)	1500 V_{RMS} 1500 V_{RMS}	0.5 mA, 50 Hz, 1 min ¹⁾ 0.5 mA, 50 Hz, 1 min ¹⁾
DCR (1/2 winding)	0.6 Ω max.	
DCR Balance	$\pm$ 0.065 Ω max.	center tap symmetry
Insertion loss	-1.2 dB max.	0.1 MHz
Return loss	-16 dB min. -10+20log(f/60) dB min. -10 dB min.	0.1 MHz ... 30 MHz 30 MHz ... 60 MHz 60 MHz ... 80 MHz
Crosstalk	-50 dB min. -50+17log(f/10) dB min.	1 MHz 10 MHz ... 100 MHz
Common-mode rejection	-50 dB typ. -15+17log(f/200) dB typ.	2 MHz 30 MHz ... 200 MHz
Weight	Approx. 5.7 g	

1) On mass manufacture will be 2 s to HV_{test}

Characteristics

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B78477P1007A114
(electrical specifications at +25 °C)

Turns ratio (primary : secondary)	1CT : 1CT $\pm 3\%$	
Inductance L	350 μ H min.	100 kHz, 100 mV, 8 mA DC bias
Voltage test V_{test} (primary : secondary)	1500 V AC	50 Hz, 1 min
Insertion loss	-1.0 dB max.	1 MHz ... 100 MHz
Return loss	-18 dB min. -14 dB min. -12 dB min. -10 dB min.	1 MHz ... 40 MHz 60 MHz 80 MHz 100 MHz
Crosstalk	-33 dB min.	1 MHz ... 100 MHz
Common-mode rejection	-30 dB typ.	1 MHz ... 100 MHz
Weight	Approx. 5.7 g	

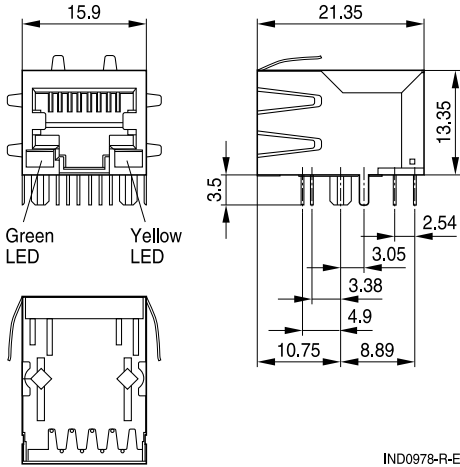
Characteristics

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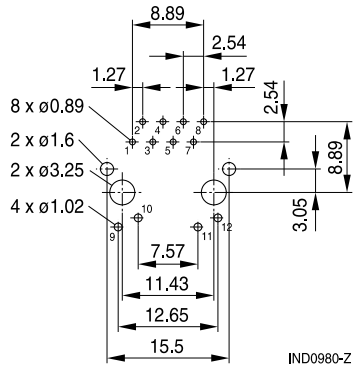
(electrical specifications at +25 °C)

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Common-mode rejection	-30 dB typ.	1 MHz ... 100 MHz
Weight	Approx. 5.7 g	

Dimensional drawing for B78477P1001A314



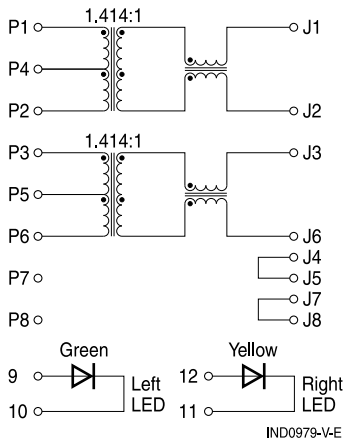
Layout recommendation (top view)



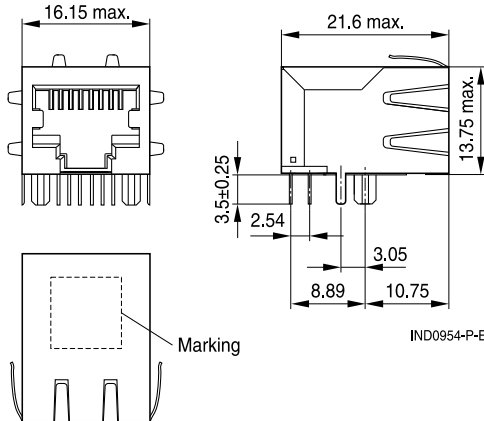
Dimensions in mm

Values without tolerances are nominal values for reference.

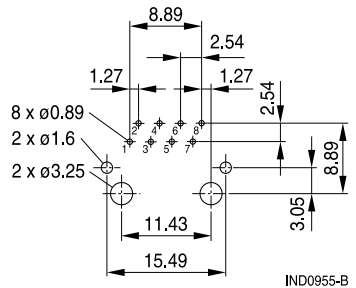
Pinning



Dimensional drawing for B78477P1002A014 and B78477P1003A014



Layout recommendation (top view)

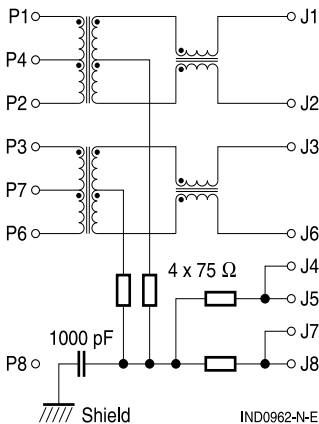


Dimensions in mm

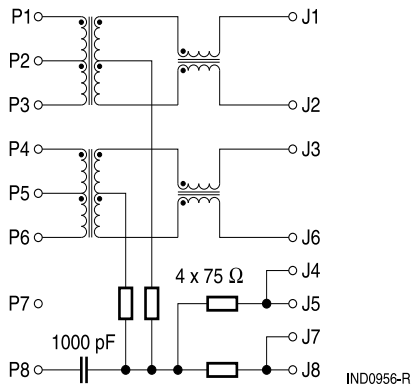
Values without tolerances are nominal values for reference.

Pinnings

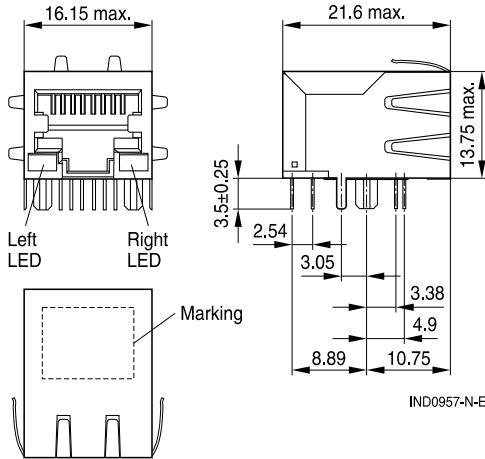
B78477P1002A014



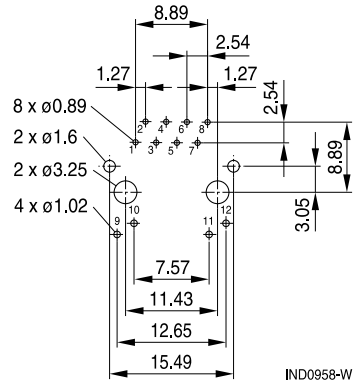
B78477P1003A014



Dimensional drawing for B78477P1004A314 and B78477P1005A314



Layout recommendation (top view)

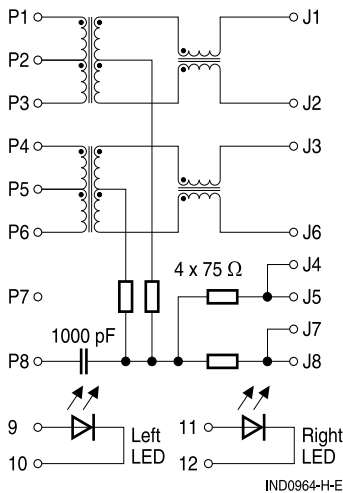


Dimensions in mm

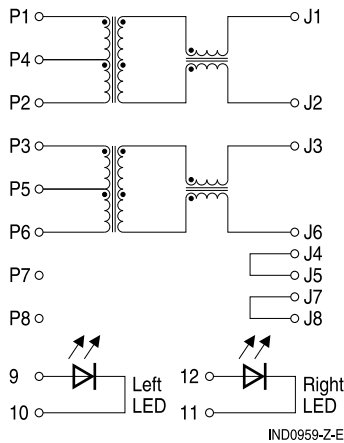
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Pinnings

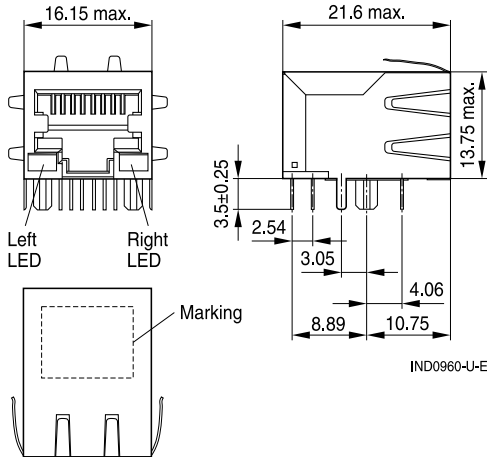
B78477P1004A314



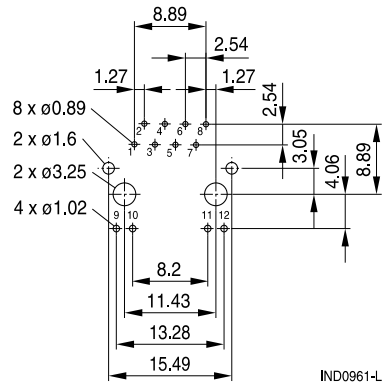
B78477P1005A314



Dimensional drawing for B78477P1006A114 and B78477P1007A114



Layout recommendation (top view)

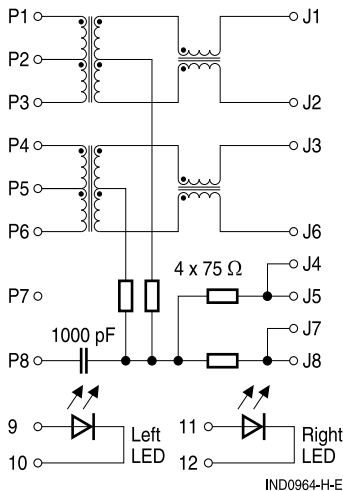


Dimensions in mm

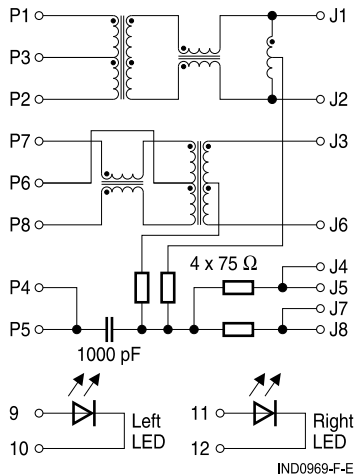
Values without tolerances are nominal values for reference.

Pinnings

B78477P1006A114



B78477P1007A114



Cautions and warnings

- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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